

Remarks

Claims 1-20 are pending. Claim 1 is amended herein. The amendment is fully supported in the specification, e.g., at page 6, line 1 – page 11, line 18.

Claims 1, 2, 7-10, 15 and 16 stand rejected under 35 U.S.C. § 103(a) as purportedly unpatentable over either of J.P. Derwent Absts. XP002118059 ('059 reference) or XP002118060 ('060 reference). Claims 3-6, 11-14 and 17-20 stand rejected under 35 U.S.C. § 103(a) as purportedly unpatentable over either of '059 or '060 taken in view of U.S. Pat. No. 4,789,699 (Kiefer). Applicants amend claim 1 herein so as to recite that the claimed composition comprises a photocured epoxy component. In light of the present amendment, Applicants request withdrawal of these rejections.

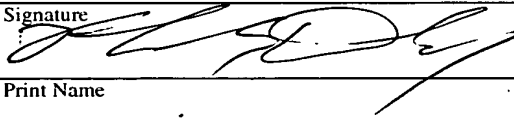
The '059 reference purports to disclose a "heat-sensitive adhesive" comprising a "thermal-hardening agent." The '060 reference purports to disclose compositions comprising a "thermosetting resin." In contrast, the present claims recite a composition comprising a photocured epoxy component. Therefore, the precursor to the claimed composition can be melt processed without premature cure. (Specification at page 6, lines 1-6). This advantage enables the formation of melt-blown microfibers for construction of non-woven webs. (Specification at page 14, line 27 – page 16, line 3.). The cited references do not teach or suggest a composition comprising a photocured epoxy component, nor do they teach the advantages of such a composition.

For all of the foregoing reasons, Applicants request withdrawal of the present rejections and allowance of the pending claims.

Respectfully submitted,

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Version With Markings to Show Changes Made

1. A pressure sensitive adhesive composition comprising:
 - a) 75 to 99.9 weight percent of a tackified thermoplastic polymer component comprising
 - 1) 1-99 weight percent of a thermoplastic polymer having substantially no epoxy-binding functions or ester functions, and
 - 2) 1-99 weight percent of a tackifier; and
 - b) 0.1 to 25 weight percent of an epoxy component comprising a photocured epoxy.